Detectors for Wide Field Imaging

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Overview

- Current status of CCDs
- Current IR detectors
- Developments in IR detectors
- Prospects





CCDs

➤ Fairchild

≥ LBNL (Hamamatsu)

≥ e2V





CCDs

✤ Fairchild

CCD486, 4kx4kx15µm

Better q.e. and slightly lower dark current than e2V CCD231 due to multi-phase pinning, but also higher readout noise

In recent discussions, Fairchild appeared to have no interest in developing larger format CCDs





Fairchild q.e. curve



CCDs

LBNL Hi-rho

Extremely red sensitive chips developed at LBNL, now also available from Hamamatsu(S10892-01) or e2V

Requires high voltage (100V) bias board, but can be incorporated into a standard controller

Some devices have been found to be extremely sensitive to ESD damage





CCDs

≥ e2V

Stable production process based on building blocks Blue, Red and High-rho devices available Anti-fringing options (variable pixel heights) Provides a simplified controller interface Avalanche gain, not yet mapped to larger formats Formats up to 8kx3k have been manufactured (larger than 4kx4k is probably lower cost for large systems) Also making 10µm pixel high-rho devices for LSST





e2V q.e. curves



e2V q.e. curves







e2V package



15µm pixels

2e- noise at 50kHz readout

5e- noise at 1MHz readout

SiC package provides 20µm flatness

CCD231-84 package





Current IR arrays

- ➢ Raytheon
 - 2kx2kx20µm VIRGO chips (VISTA)
 - 2.5µm cut-off, good q.e, poor cosmetics
 - Low cost option, mixed experience from VISTA
 - 3-edge-buttable
- > Teledyne
 - 2kx2kx18µm HAWAII-2RG
 - 2.5 or $1.7\mu m$ cut-off, substrate removed
 - 3-edge buttable
 - Highly functional ROIC with option for multiple fast readout windows to prevent saturation and persistence
 - SIDECAR integrated ASIC controller





Array Fabrication Technology

- HgCdTe layer grown on ZnCdTe substrates (good lattice match) using MBE (RVS still using LPE)
- Detector layer hybridised to Si CMOS ROIC
- Limitations on array size, performance and yield/lifetime (-> cost)









Channel cross-talk (from ESO's X-Shooter, courtesy G. Finger)







▶ Fringing due to substrate...



₽ Persistence...

Remnant image of bright source in preceding exposure sometimes visible for hours after event.





- Inter-pixel capacitance
 - Leads to over-estimation of system gain, and hence quantum efficiency
- Photo-emission defects
 - Occasionally individual pixels seen to act as bright IR LEDs
- ➤ Catastrophic failures...
 - A large number of early arrays have now been observed to delaminate after repeated cold cycling





New developments in IR

ESA TRP for Cosmic Visions

 Promote development of EU competitor to Teledyne for next generation space missions
 SELEX-Galileo
 QinetiQ





Evolution of 2D arrays at SELEX

by Merlin MWIR

OSPREY 384 x 288 24µm pitch MW and LW EAGLE 640 x 512 24µm pitch MW and LW HAWK 640 X 512 16µm pitch MW and LW Dry etched mesas MERLIN 1024 x 768 16µm pitch MW and LW Dry etched mesas CONDOR 640 x 512 24µm pitch Two Colour Dry etched mesas

Larger area Smaller pixels Multicolour detectors









SELEX Capabilities

- HgCdTe grown by MOVPE on GaAs substrates then hybridised
- GaAs 100x less expensive than lattice matched CdZnTe
- >Multiple suppliers (CZT has limited no. of commercial suppliers)
- >Wafer scale (150mm) processing using standard semiconductor equipment
- Few mask stages
- >New bump bonder being installed. 150mm array end-end capability
- Should be able to produce low-cost equivalent of HAWAII-2RG devices





Two-Colour Detectors





MW Absorber Barrier laver

LW Absorber

Surface passivation



Evolution of 2D arrays at QinetiQ

HgCdTe as IR detector invented at Malvern in 1959

128 x 128 HgCdTe hybridised on Si 55µm pitch LW (10µm) 1024 x 768 HgCdTe hybridised on Si 26µm pitch LW (9.6µm) **Dual band arrays** 30µm pitch MW and LW two capacitors/pixel









Developments - QinetiQ

- MOVPE growth at high T gives much more control of growth environment than MBE process
- Direct growth onto ROIC mesas no substrate
- » Si substrates ultimately available up to 300mm
- Key technology is the survivability of the ROIC structure in the MOVPE growth environment





Optical micrograph showing ROIC pixels



Crystalline Si surface growth window

Integrated circuits surrounding growth window





•Scanning electron micrograph

Crystalline

Polycrystalline

MCT

MCT in

window areas





•Scanning electron micrograph of part of processed FPA



Crystalline MCT mesas

Silicon circuit





•Example of prototype FPA









Test Pixel Growth

n-type contact



wafer



p-type contact (bottom)



 $75\mu m$ pixel grown in $100\mu m$ growth window on a test

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Test pixel transmission (inferred from back-illuminated test)







Developments - QinetiQ

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- Direct growth onto ROIC mesas no substrate
- Si substrates ultimately available up to 300mm
- Key technology is the survivability of the ROIC structure in the MOVPE growth environment
- ➢ Good SW (1-2.5µm) material performance demonstrated
- » Larger (36µm) pixels optimal for some ELT instruments
 - NB for 150mm wafers and 50µm pixels = 2048x2048 array (c.f. end of VISTA talk)
- Key specifications appropriate to ELT instruments can be met Good q.e. & linearity
- Not able to measure dark current at astronomical level
- Key aims are to demonstrate modest array-scale growth of SW device on an appropriate ROIC





Small pitch IIDC





Pixel growth area ~18.5µm x 18.4µm





20µm

(gnd) (gnd)

(in)

logy

(in)

Optical concentrators – immersion lens





One immersion lens / 4 pixels







CX06XI10 0.6µm W process
Pixel growth area ~13µm x 13µm
Fill factor ~ 19%





Optical concentrators - cones



Low gain option with area gain of 4
Substantially reduces dark current/"pixel"









Prospects

ESA TRP announced last week for NIR detector development

- Terms look favourable to both SELEX and QinetiQ development routes
- SELEX probably provides the best route to a quick replacement for a H-2RG/H-4RG type device...
- QinetiQ probably more interesting for widefield imaging considerations: possibility of migrating to 12" silicon wafer scale devices.





Longer term...?

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Flat-screen light bulbs switch on

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By Jason Palmer Science and technology reporter, BBC News



The devices are flat - another reason they are desirable as light sources

Researchers have demonstrated white, organic light-emitting diode (OLED) sources with the same efficiency as fluorescent light bulbs.

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